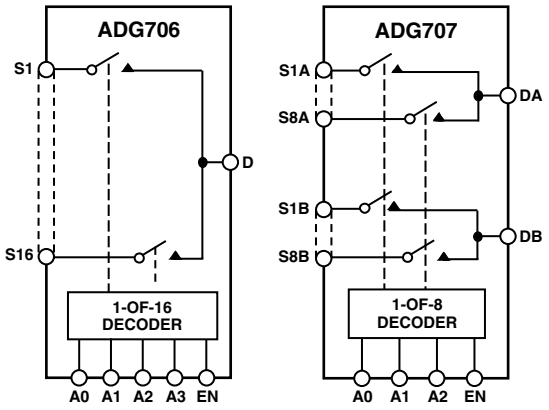
CMOS, +1.8 V to +5.5 V/±2.5 V, 2.5 Ω Low-Voltage, 8-/16-Channel Multiplexers

ADG706/ADG707

FEATURES
+1.8 V to +5.5 V Single Supply
±2.5 V Dual Supply
2.5 Ω ON Resistance
0.5 Ω ON Resistance Flatness
100 pA Leakage Currents
40 ns Switching Times
Single 16-to-1 Multiplexer ADG706
Differential 8-to-1 Multiplexer ADG707
28-Lead TSSOP Package
Low-Power Consumption
TTL/CMOS-Compatible Inputs

APPLICATIONS
Data Acquisition Systems
Communication Systems
Relay Replacement
Audio and Video Switching
Battery-Powered Systems

FUNCTIONAL BLOCK DIAGRAMS



GENERAL DESCRIPTION

The ADG706 and ADG707 are low-voltage, CMOS analog multiplexers comprising 16 single channels and eight differential channels, respectively. The ADG706 switches one of 16 inputs (S1–S16) to a common output, D, as determined by the 4-bit binary address lines A0, A1, A2, and A3. The ADG707 switches one of eight differential inputs to a common differential output as determined by the 3-bit binary address lines A0, A1, and A2. An EN input on both devices is used to enable or disable the device. When disabled, all channels are switched OFF.

Low-power consumption and operating supply range of 1.8 V to 5.5 V make the ADG706 and ADG707 ideal for battery-powered, portable instruments. All channels exhibit break-before-make switching action preventing momentary shorting when switching channels. These devices are also designed to operate from a dual supply of ±2.5 V.

These multiplexers are designed on an enhanced submicron process that provides low-power dissipation yet gives high switching speed, very low ON resistance, and leakage currents. ON resistance is in the region of a few ohms and is closely matched between switches and very flat over the full signal range. These parts can operate equally well as either multiplexers or demultiplexers and have an input signal range that extends to the supplies.

The ADG706 and ADG707 are available in small 28-lead TSSOP packages.

PRODUCT HIGHLIGHTS

1. Single-/dual-supply operation. The ADG706 and ADG707 are fully specified and guaranteed with 3 V and 5 V single-supply and ±2.5 V dual-supply rails.
2. Low ON resistance (2.5 Ω typical)
3. Low-power consumption (<0.01 μW)
4. Guaranteed break-before-make switching action
5. Small 28-lead TSSOP package

REV. B

One Technology Way, P.O. Box 9106, Norwood, MA 02062-9106, U.S.A.
Tel: 781/329-4700 **www.analog.com**
Fax: 781/326-8703

ADG706/ADG707–SPECIFICATIONS[1] (V_{DD} = 5 V ± 10%, V_{SS} = 0 V, GND = 0 V, unless otherwise noted.)

Parameter	25°C	–40°C to +85°C	Unit	Test Conditions/Comments
ANALOG SWITCH				
Analog Signal Range		0 V to V_{DD}	V	
ON Resistance (R_{ON})	2.5		Ω typ	V_S = 0 V to V_{DD}, I_{DS} = 10 mA;
	4.5	5	Ω max	Test Circuit 1
ON Resistance Match Between		0.3	Ω typ	V_S = 0 V to V_{DD}, I_{DS} = 10 mA
Channels (ΔR_{ON})		0.8	Ω max	
ON Resistance Flatness ($R_{FLAT(ON)}$)	0.5		Ω typ	V_S = 0 V to V_{DD}, I_{DS} = 10 mA
		1.2	Ω max	
LEAKAGE CURRENTS				V_{DD} = 5.5 V
Source OFF Leakage I_S (OFF)	±0.01		nA typ	V_D = 4.5 V/1 V, V_S = 1 V/4.5 V;
	±0.1	±0.3	nA max	Test Circuit 2
Drain OFF Leakage I_D (OFF)	±0.01		nA typ	V_D = 4.5 V/1 V, V_S = 1 V/4.5 V;
ADG706	±0.4	±1.5	nA max	Test Circuit 3
ADG707	±0.2	±1	nA max	
Channel ON Leakage I_D, I_S (ON)	±0.01		nA typ	V_D = V_S = 1 V, or 4.5 V;
ADG706	±0.4	±1.5	nA max	Test Circuit 4
ADG707	±0.2	±1	nA max	
DIGITAL INPUTS				
Input High Voltage, V_{INH}		2.4	V min	
Input Low Voltage, V_{INL}		0.8	V max	
Input Current				
I_{INL} or I_{INH}	0.005		μA typ	V_{IN} = V_{INL} or V_{INH}
		±0.1	μA max	
C_{IN}, Digital Input Capacitance	5		pF typ	
DYNAMIC CHARACTERISTICS[2]				
$t_{TRANSITION}$	40		ns typ	R_L = 300 Ω, C_L = 35 pF, Test Circuit 5;
		60	ns max	V_{S1} = 3 V/0 V, V_{S16} = 0 V/3 V
Break-Before-Make Time Delay, t_D	30		ns typ	R_L = 300 Ω, C_L = 35 pF;
		1	ns min	V_S = 3 V, Test Circuit 6
t_{ON} (EN)	32		ns typ	R_L = 300 Ω, C_L = 35 pF;
		50	ns max	V_S = 3 V, Test Circuit 7
t_{OFF} (EN)	10		ns typ	R_L = 300 Ω, C_L = 35 pF;
		14	ns max	V_S = 3 V, Test Circuit 7
Charge Injection	±5		pC typ	V_S = 1 V, R_S = 0 Ω, C_L = 1 nF; Test Circuit 8
OFF Isolation	–60		dB typ	R_L = 50 Ω, C_L = 5 pF, f = 10 MHz;
	–80		dB typ	R_L = 50 Ω, C_L = 5 pF, f = 1 MHz; Test Circuit 9
Channel-to-Channel Crosstalk	–60		dB typ	R_L = 50 Ω, C_L = 5 pF, f = 10 MHz;
	–80		dB typ	R_L = 50 Ω, C_L = 5 pF, f = 1 MHz; Test Circuit 10
–3 dB Bandwidth				
ADG706	25		MHz typ	R_L = 50 Ω, C_L = 5 pF, Test Circuit 9
ADG707	36		MHz typ	R_L = 50 Ω, C_L = 5 pF, Test Circuit 9
C_S (OFF)	13		pF typ	f = 1 MHz
C_D (OFF)				
ADG706	180		pF typ	f = 1 MHz
ADG707	90		pF typ	f = 1 MHz
C_D, C_S (ON)				
ADG706	200		pF typ	f = 1 MHz
ADG707	100		pF typ	f = 1 MHz
POWER REQUIREMENTS				V_{DD} = 5.5 V
I_{DD}	0.001		μA typ	Digital Inputs = 0 V or 5.5 V
		1.0	μA max	

NOTES

[1]Temperature range is –40°C to +85°C.

[2]Guaranteed by design, not subject to production test.

Specifications subject to change without notice.

SPECIFICATIONS[1] (V_{DD} = 3 V ± 10%, V_{SS} = 0 V, GND = 0 V, unless otherwise noted.)

Parameter	25°C	–40°C to +85°C	Unit	Test Conditions/Comments
ANALOG SWITCH				
Analog Signal Range		0 V to V_{DD}	V	
ON Resistance (R_{ON})	6		Ω typ	V_S = 0 V to V_{DD}, I_{DS} = 10 mA;
	11	12	Ω max	Test Circuit 1
ON Resistance Match Between		0.4	Ω typ	V_S = 0 V to V_{DD}, I_{DS} = 10 mA
Channels (ΔR_{ON})		1.2	Ω max	
ON Resistance Flatness ($R_{FLAT(ON)}$)		3	Ω typ	V_S = 0 V to V_{DD}, I_{DS} = 10 mA
LEAKAGE CURRENTS				V_{DD} = 3.3 V
Source OFF Leakage I_S (OFF)	±0.01		nA typ	V_S = 3 V/1 V, V_D = 1 V/3 V;
	±0.1	±0.3	nA max	Test Circuit 2
Drain OFF Leakage I_D (OFF)	±0.01		nA typ	V_S = 3 V/1 V, V_D = 1 V/3 V;
ADG706	±0.4	±1.5	nA max	Test Circuit 3
ADG707	±0.2	±1	nA max	
Channel ON Leakage I_D, I_S (ON)	±0.01		nA typ	V_S = V_D = 1 V or 3 V;
ADG706	±0.4	±1.5	nA max	Test Circuit 4
ADG707	±0.2	±1	nA max	
DIGITAL INPUTS				
Input High Voltage, V_{INH}		2.0	V min	
Input Low Voltage, V_{INL}		0.8	V max	
Input Current				
I_{INL} or I_{INH}	0.005		μA typ	V_{IN} = V_{INL} or V_{INH}
		±0.1	μA max	
C_{IN}, Digital Input Capacitance	5		pF typ	
DYNAMIC CHARACTERISTICS[2]				
$t_{TRANSITION}$	45		ns typ	R_L = 300 Ω, C_L = 35 pF, Test Circuit 5
		75	ns max	V_{S1} = 2 V/0 V, V_{S16} = 0 V/2 V
Break-Before-Make Time Delay, t_D	30		ns typ	R_L = 300 Ω, C_L = 35 pF;
		1	ns min	V_S = 2 V, Test Circuit 6
t_{ON} (EN)	40		ns typ	R_L = 300 Ω, C_L = 35 pF;
		70	ns max	V_S = 2 V, Test Circuit 7
t_{OFF} (EN)	20		ns typ	R_L = 300 Ω, C_L = 35 pF;
		28	ns max	V_S = 2 V, Test Circuit 7
Charge Injection	±5		pC typ	V_S = 1 V, R_S = 0 Ω, C_L = 1 nF; Test Circuit 8
OFF Isolation	–60		dB typ	R_L = 50 Ω, C_L = 5 pF, f = 10 MHz;
	–80		dB typ	R_L = 50 Ω, C_L = 5 pF, f = 1 MHz; Test Circuit 9
Channel-to-Channel Crosstalk	–60		dB typ	R_L = 50 Ω, C_L = 5 pF, f = 10 MHz;
	–80		dB typ	R_L = 50 Ω, C_L = 5 pF, f = 1 MHz; Test Circuit 10
–3 dB Bandwidth				
ADG706	25		MHz typ	R_L = 50 Ω, C_L = 5 pF, Test Circuit 9
ADG707	36		MHz typ	R_L = 50 Ω, C_L = 5 pF, Test Circuit 9
C_S (OFF)	13		pF typ	f = 1 MHz
C_D (OFF)				
ADG706	180		pF typ	f = 1 MHz
ADG707	90		pF typ	f = 1 MHz
C_D, C_S (ON)				
ADG706	200		pF typ	f = 1 MHz
ADG707	100		pF typ	f = 1 MHz
POWER REQUIREMENTS				V_{DD} = 3.3 V
I_{DD}	0.001		μA typ	Digital Inputs = 0 V or 3.3 V
		1.0	μA max	

NOTES

[1]Temperature range is –40°C to +85°C.

[2]Guaranteed by design, not subject to production test.

Specifications subject to change without notice.

DUAL SUPPLY[1] (V_{DD} = +2.5 V ±10%, V_{SS} = –2.5 V ±10%, GND = 0 V, unless otherwise noted.)

Parameter	25°C	–40°C to +85°C	Unit	Test Conditions/Comments
ANALOG SWITCH				
Analog Signal Range		V_{SS} to V_{DD}	V	
ON Resistance (R_{ON})	2.5		Ω typ	V_S = V_{SS} to V_{DD}, I_{DS} = 10 mA;
	4.5	5	Ω max	Test Circuit 1
ON Resistance Match Between		0.3	Ω typ	V_S = V_{SS} to V_{DD}, I_{DS} = 10 mA
Channels (ΔR_{ON})		0.8	Ω max	
ON Resistance Flatness ($R_{FLAT(ON)}$)	0.5		Ω typ	V_S = V_{SS} to V_{DD}, I_{DS} = 10 mA
		1.2	Ω max	
LEAKAGE CURRENTS				V_{DD} = +2.75 V, V_{SS} = –2.75 V
Source OFF Leakage I_S (OFF)	±0.01		nA typ	V_S = +2.25 V/–1.25 V, V_D = –1.25 V/+2.25 V;
	±0.1	±0.3	nA max	Test Circuit 2
Drain OFF Leakage I_D (OFF)	±0.01		nA typ	V_S = +2.25 V/–1.25 V, V_D = –1.25 V/+2.25 V;
ADG706	±0.4	±1.5	nA max	Test Circuit 3
ADG707	±0.2	±1	nA max	
Channel ON Leakage I_D, I_S (ON)	±0.01		nA typ	V_S = V_D = +2.25 V/–1.25 V, Test Circuit 4
ADG706	±0.4	±1.5	nA max	
ADG707	±0.2	±1	nA max	
DIGITAL INPUTS				
Input High Voltage, V_{INH}		1.7	V min	
Input Low Voltage, V_{INL}		0.7	V max	
Input Current				
I_{INL} or I_{INH}	0.005		μA typ	V_{IN} = V_{INL} or V_{INH}
		±0.1	μA max	
C_{IN}, Digital Input Capacitance	5		pF typ	
DYNAMIC CHARACTERISTICS[2]				
$t_{TRANSITION}$	40		ns typ	R_L = 300 Ω, C_L = 35 pF, Test Circuit 5
		60	ns max	V_{S1} = 1.5 V/0 V, V_{S16} = 0 V/1.5 V
Break-Before-Make Time Delay, t_D	15		ns typ	R_L = 300 Ω, C_L = 35 pF;
		1	ns min	V_S = 1.5 V, Test Circuit 6
t_{ON} (EN)	32		ns typ	R_L = 300 Ω, C_L = 35 pF;
		50	ns max	V_S = 1.5 V, Test Circuit 7
t_{OFF} (EN)	16		ns typ	R_L = 300 Ω, C_L = 35 pF;
		26	ns max	V_S = 1.5 V, Test Circuit 7
Charge Injection	±8		pC typ	V_S = 0 V, R_S = 0 Ω, C_L = 1 nF; Test Circuit 8
OFF Isolation	–60		dB typ	R_L = 50 Ω, C_L = 5 pF, f = 10 MHz;
	–80		dB typ	R_L = 50 Ω, C_L = 5 pF, f = 1 MHz; Test Circuit 9
Channel-to-Channel Crosstalk	–60		dB typ	R_L = 50 Ω, C_L = 5 pF, f = 10 MHz;
	–80		dB typ	R_L = 50 Ω, C_L = 5 pF, f = 1 MHz; Test Circuit 10
–3 dB Bandwidth				
ADG706	25		MHz typ	R_L = 50 Ω, C_L = 5 pF, Test Circuit 9
ADG707	36		MHz typ	R_L = 50 Ω, C_L = 5 pF, Test Circuit 9
C_S (OFF)	13		pF typ	f = 1 MHz
C_D (OFF)				
ADG706	180		pF typ	f = 1 MHz
ADG707	90		pF typ	f = 1 MHz
C_D, C_S (ON)				
ADG706	200		pF typ	f = 1 MHz
ADG707	100		pF typ	f = 1 MHz
POWER REQUIREMENTS				
I_{DD}	0.001		μA typ	V_{DD} = +2.75 V
		1.0	μA max	Digital Inputs = 0 V or 2.75 V
I_{SS}	0.001		μA typ	V_{SS} = –2.75 V
		1.0	μA max	Digital Inputs = 0 V or 2.75 V

NOTES
[1]Temperature range is –40°C to +85°C.
[2]Guaranteed by design, not subject to production test.

Specifications subject to change without notice.

ABSOLUTE MAXIMUM RATINGS[1]
(T_A = 25°C unless otherwise noted.)

V_{DD} to V_{SS} . . . . . 7 V
V_{DD} to GND . . . . . –0.3 V to +7 V
V_{SS} to GND . . . . . +0.3 V to –3.5 V
Analog Inputs[2] . . . . . V_{SS} – 0.3 V to V_{DD} + 0.3 V or 30 mA, Whichever Occurs First
Digital Inputs[2] . . . . . –0.3 V to V_{DD} + 0.3 V or 30 mA, Whichever Occurs First
Peak Current, S or D . . . . . 100 mA (Pulsed at 1 ms, 10% Duty Cycle max)
Continuous Current, S or D . . . . . 30 mA
Operating Temperature Range
Industrial . . . . . –40°C to +85°C
Storage Temperature Range . . . . . –65°C to +150°C
Junction Temperature . . . . . 150°C
TSSOP Package
θ_{JA} Thermal Impedance . . . . . 97.9°C/W
θ_{JC} Thermal Impedance . . . . . 14°C/W
Lead Temperature, Soldering (10 sec) . . . . . 300°C
IR Reflow, Peak Temperature . . . . . 220°C

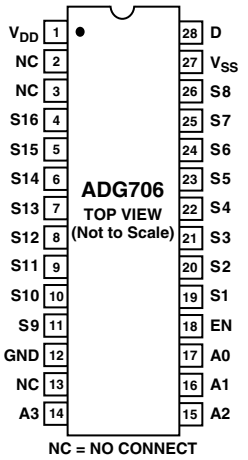
NOTES
[1]Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other conditions above those listed in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability. Only one absolute maximum rating may be applied at any one time.
[2]Overvoltages at A, EN, S, or D will be clamped by internal diodes. Current should be limited to the maximum ratings given.

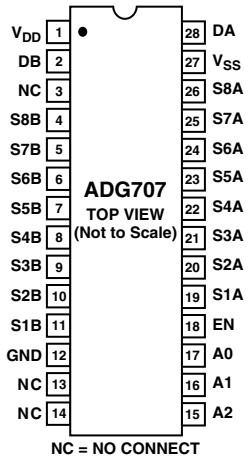
ORDERING GUIDE

Model[1]	Temperature Range	Package Description	Package Option
ADG706BRU	–40°C to +85°C	28-Lead Thin Shrink Small Outline Package [TSSOP]	RU-28
ADG706BRU-REEL7	–40°C to +85°C	28-Lead Thin Shrink Small Outline Package [TSSOP]	RU-28
ADG706BRUZ	–40°C to +85°C	28-Lead Thin Shrink Small Outline Package [TSSOP]	RU-28
ADG706BRUZ-REEL	–40°C to +85°C	28-Lead Thin Shrink Small Outline Package [TSSOP]	RU-28
ADG706BRUZ-REEL7	–40°C to +85°C	28-Lead Thin Shrink Small Outline Package [TSSOP]	RU-28
ADG707BRU	–40°C to +85°C	28-Lead Thin Shrink Small Outline Package [TSSOP]	RU-28
ADG707BRU-REEL	–40°C to +85°C	28-Lead Thin Shrink Small Outline Package [TSSOP]	RU-28
ADG707BRUZ	–40°C to +85°C	28-Lead Thin Shrink Small Outline Package [TSSOP]	RU-28
ADG707BRUZ-REEL7	–40°C to +85°C	28-Lead Thin Shrink Small Outline Package [TSSOP]	RU-28

[1] Z = RoHS Compliant Part.

PIN CONFIGURATIONS





CAUTION

ESD (electrostatic discharge) sensitive device. Electrostatic charges as high as 4000 V readily accumulate on the human body and test equipment and can discharge without detection. Although the ADG706/ADG707 features proprietary ESD protection circuitry, permanent damage may occur on devices subjected to high energy electrostatic discharges. Therefore, proper ESD precautions are recommended to avoid performance degradation or loss of functionality.

Table I. ADG706 Truth Table

A3	A2	A1	A0	EN	ON Switch
X	X	X	X	0	NONE
0	0	0	0	1	1
0	0	0	1	1	2
0	0	1	0	1	3
0	0	1	1	1	4
0	1	0	0	1	5
0	1	0	1	1	6
0	1	1	0	1	7
0	1	1	1	1	8
1	0	0	0	1	9
1	0	0	1	1	10
1	0	1	0	1	11
1	0	1	1	1	12
1	1	0	0	1	13
1	1	0	1	1	14
1	1	1	0	1	15
1	1	1	1	1	16

X = Don't Care

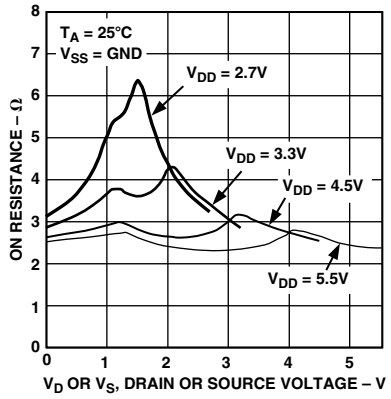
Table II. ADG707 Truth Table

A2	A1	A0	EN	ON Switch Pair
X	X	X	0	NONE
0	0	0	1	1
0	0	1	1	2
0	1	0	1	3
0	1	1	1	4
1	0	0	1	5
1	0	1	1	6
1	1	0	1	7
1	1	1	1	8

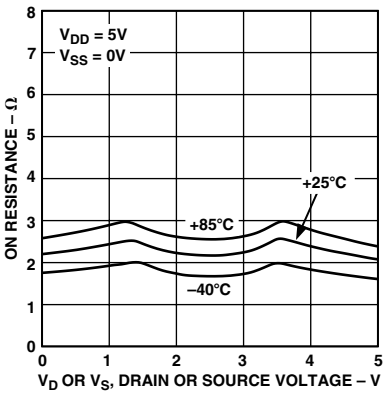
X = Don't Care

TERMINOLOGY

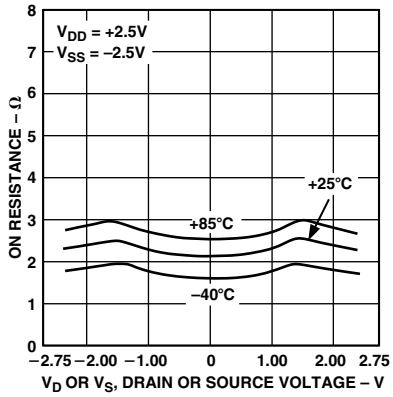
V_{DD}	Most positive power supply potential
V_{SS}	Most negative power supply in a dual-supply application. In single-supply applications, this should be tied to ground at the device.
I_{DD}	Positive supply current
I_{SS}	Negative supply current
GND	Ground (0 V) reference
S	Source terminal. May be an input or output.
D	Drain terminal. May be an input or output.
AX	Logic control input
EN	Active high device enable
V_D (V_S)	Analog voltage on terminals D, S
R_{ON}	Ohmic resistance between D and S
ΔR_{ON}	ON Resistance match between any two channels, i.e., R_{ON}max – R_{ON}min
$R_{FLAT(ON)}$	Flatness is defined as the difference between the maximum and minimum value of ON resistance as measured over the specified analog signal range.
I_S (OFF)	Source leakage current with the Switch "OFF"
I_D (OFF)	Drain leakage current with the Switch "OFF"
I_D, I_S (ON)	Channel leakage current with the Switch "ON"
V_{INL}	Maximum input voltage for Logic "0"
V_{INH}	Minimum input voltage for Logic "1"
I_{INL}(I_{INH})	Input current of the digital input
C_S (OFF)	"OFF" Switch Source Capacitance. Measured with reference to ground.
C_D (OFF)	"OFF" Switch drain capacitance. Measured with reference to ground.
C_D, C_S (ON)	"ON" Switch capacitance. Measured with reference to ground.
C_{IN}	Digital input capacitance
$t_{TRANSITION}$	Delay time measured between the 50% and 90% points of the digital inputs and the switch "ON" condition when switching from one address state to another
t_{ON} (EN)	Delay time between the 50% and 90% points of the EN digital input and the Switch "ON" condition
t_{OFF} (EN)	Delay time between the 50% and 90% points of the EN digital input and the Switch "OFF" condition
t_{OPEN}	"OFF" Time measured between the 80% points of both switches when switching from one address state to another
Charge Injection	Measure of the glitch impulse transferred from the digital input to the analog output during switching
OFF Isolation	Measure of unwanted signal coupling through an "OFF" switch
Crosstalk	Measure of unwanted signal that is coupled through from one channel to another as a result of parasitic capacitance
Bandwidth	Frequency at which the output is attenuated by 3 dB
ON Response	Frequency response of the "ON" Switch
Insertion Loss	Loss due to the ON Resistance of the switch



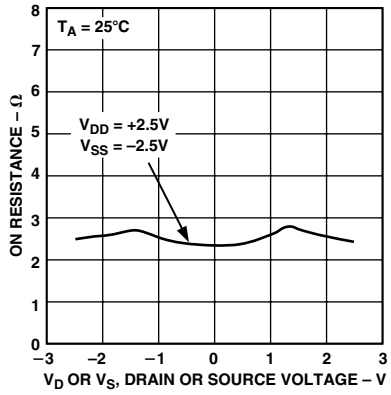
TPC 1. ON Resistance as a Function of V_D (V_S) for Single Supply



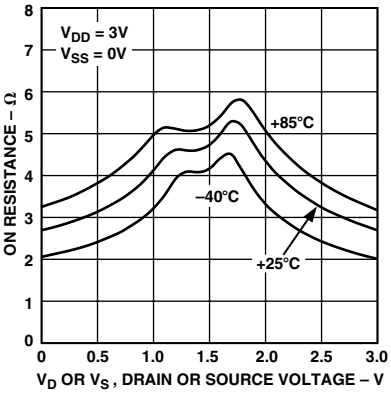
TPC 2. ON Resistance as a Function of V_D (V_S) for Different Temperatures, Single Supply



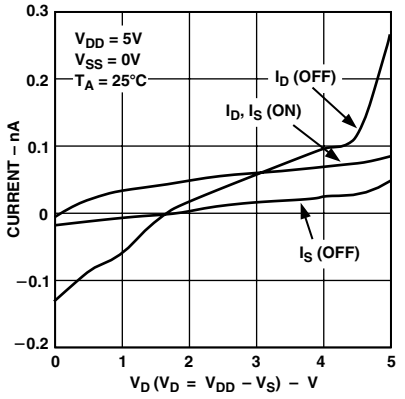
TPC 3. ON Resistance as a Function of V_D (V_S) for Different Temperatures, Dual Supply



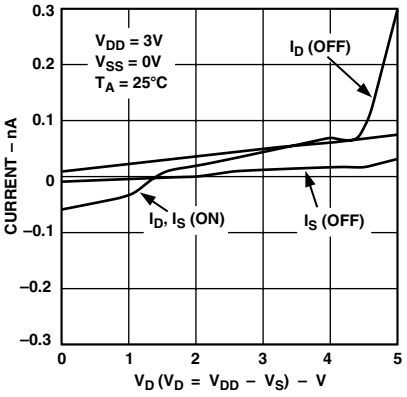
TPC 4. ON Resistance as a Function of V_D (V_S) for Dual Supply



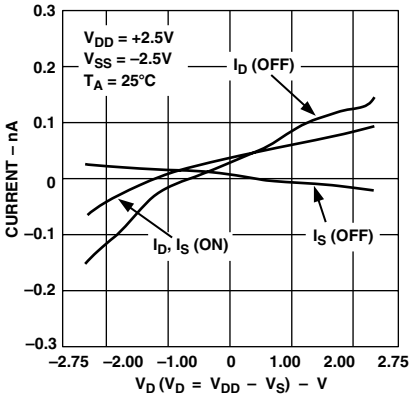
TPC 5. ON Resistance as a Function of V_D (V_S) for Different Temperatures, Single Supply



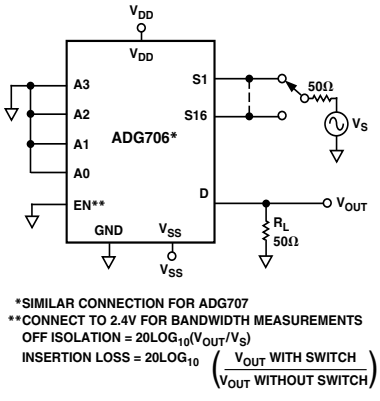
TPC 6. Leakage Currents as a Function of V_D (V_S)



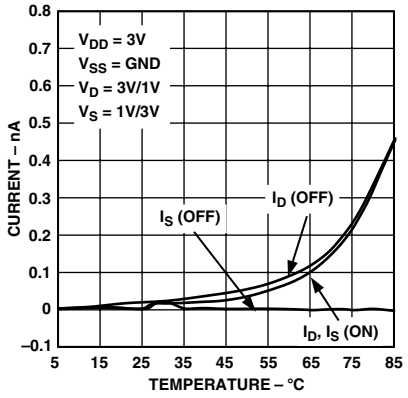
TPC 7. Leakage Currents as a Function of V_D (V_S)



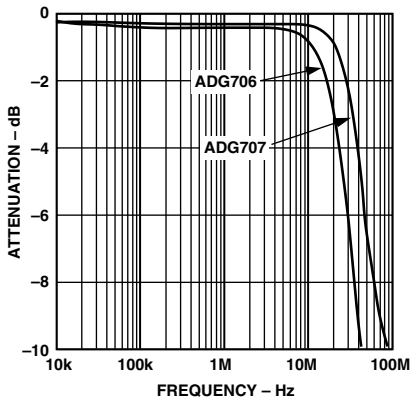
TPC 8. Leakage Currents as a Function of V_D (V_S)



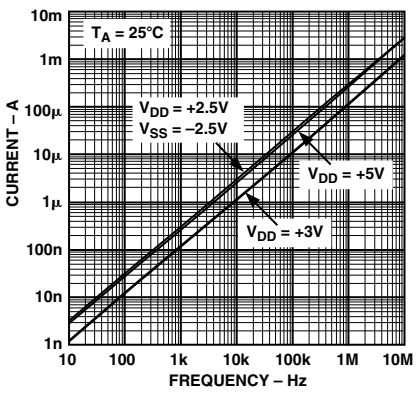
TPC 9. Leakage Currents as a Function of Temperature



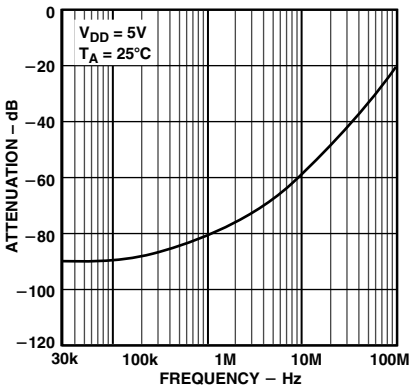
TPC 10. Leakage Currents as a Function of Temperature



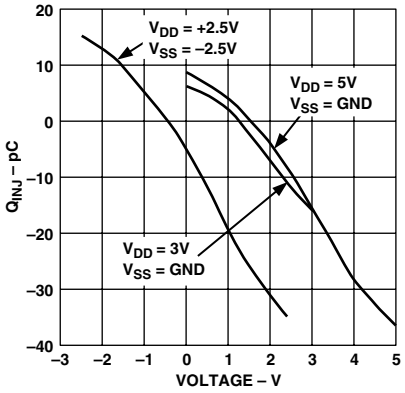
TPC 11. ON Response vs. Frequency



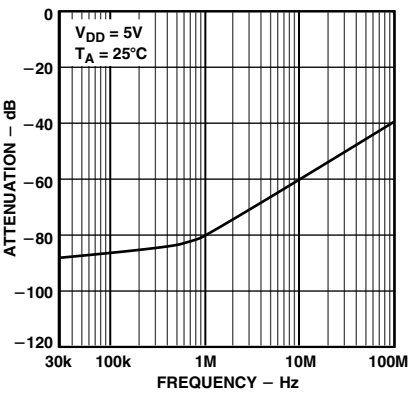
TPC 12. Supply Currents vs. Input Switching Frequency



TPC 13. OFF Isolation vs. Frequency

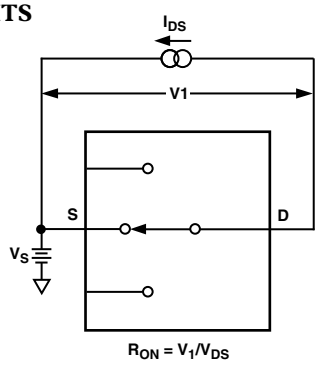


TPC 14. Charge Injection vs. Source Voltage

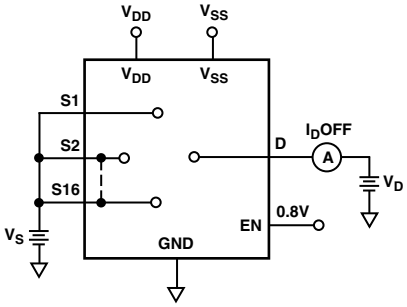


TPC 15. Crosstalk vs. Frequency

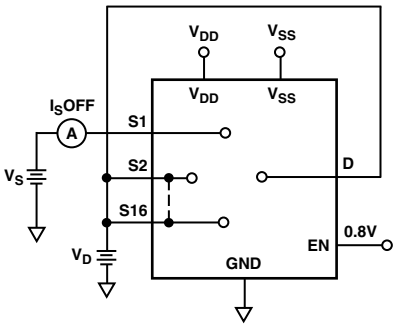
TEST CIRCUITS



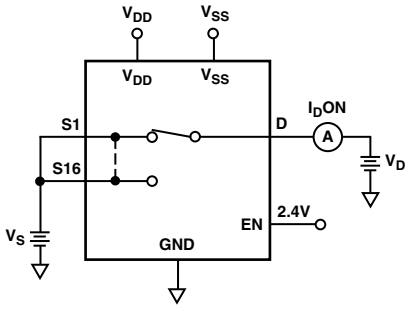
Test Circuit 1. ON Resistance



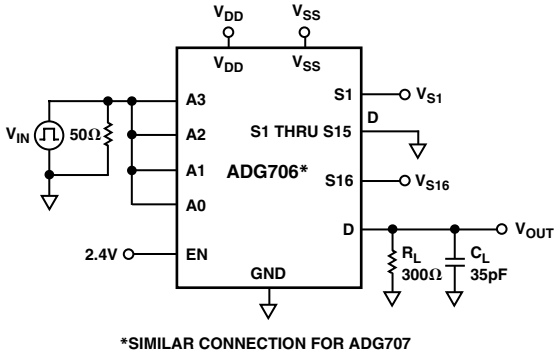
Test Circuit 3. I_D (OFF)

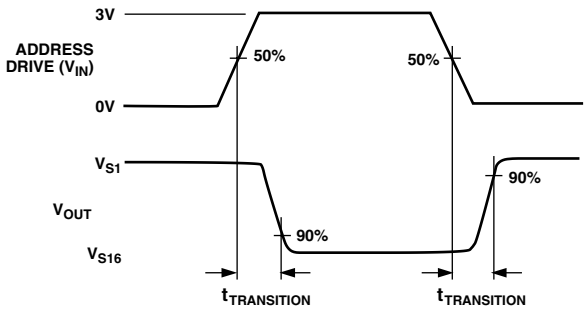


Test Circuit 2. I_S (OFF)

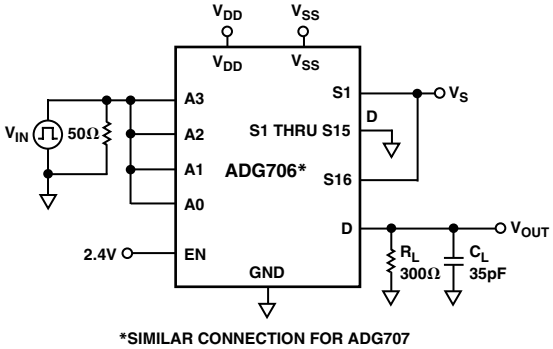


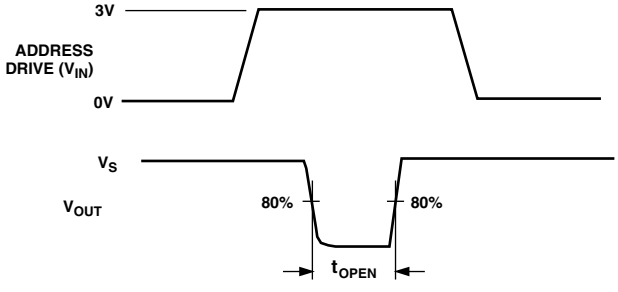
Test Circuit 4. I_D (ON)



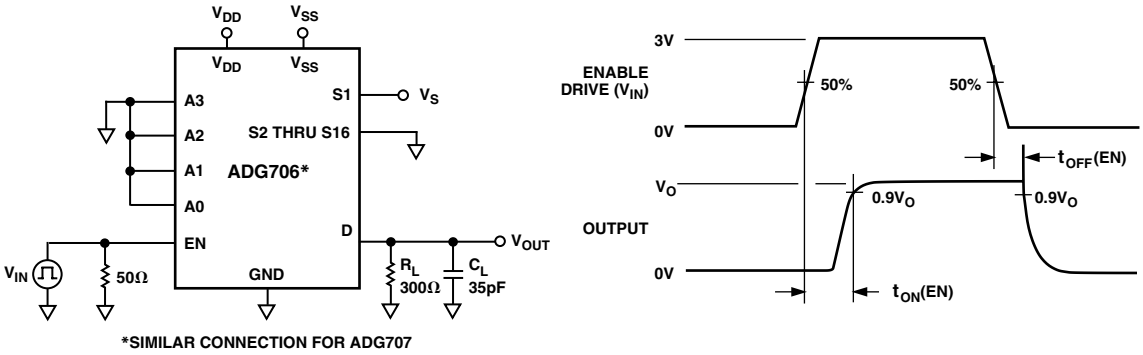


Test Circuit 5. Switching Time of Multiplexer, $t_{TRANSITION}$

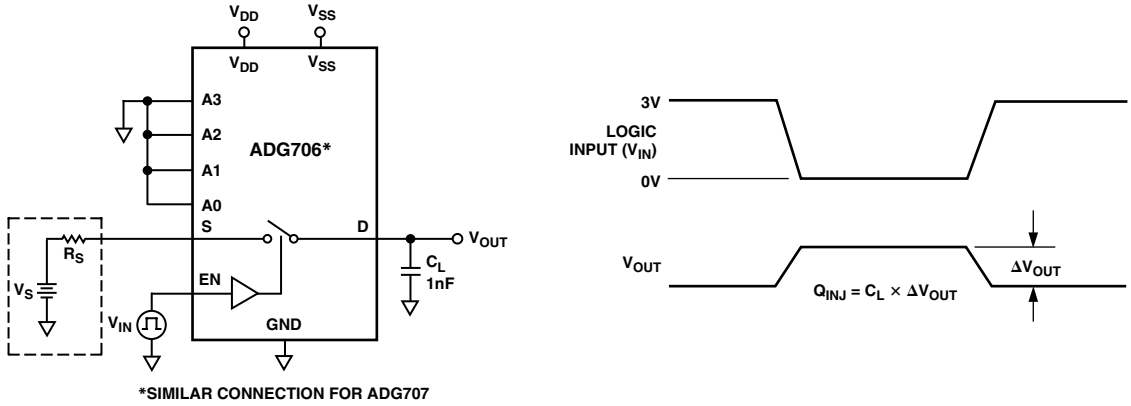




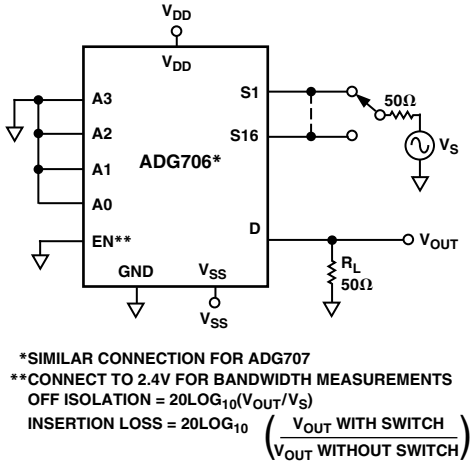
Test Circuit 6. Break-Before-Make Delay, t_{OPEN}



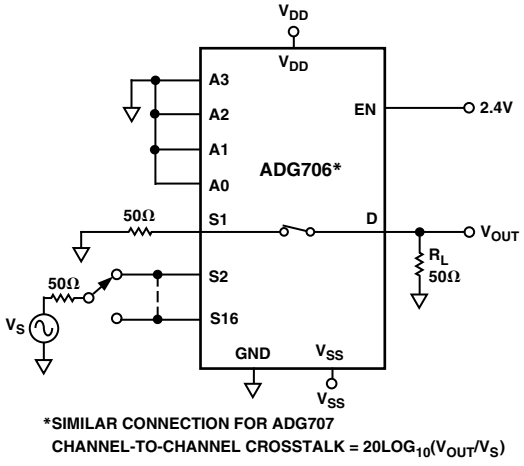
Test Circuit 7. Enable Delay, t_{ON} (EN), t_{OFF} (EN)



Test Circuit 8. Charge Injection

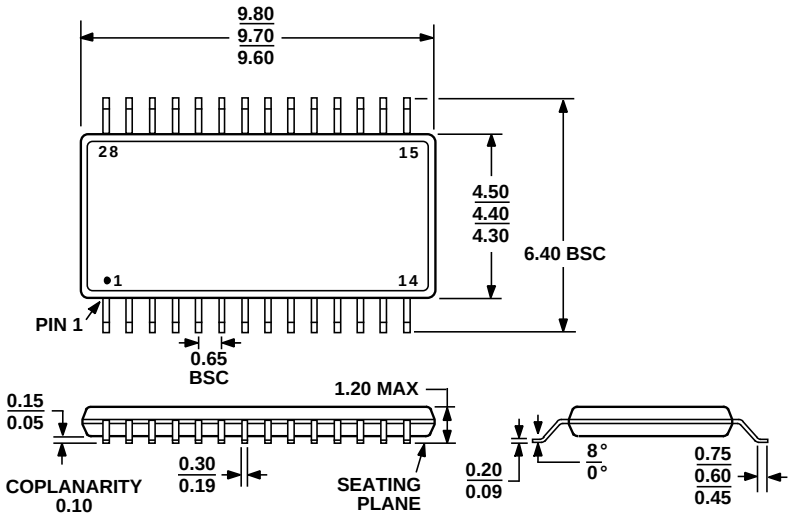


Test Circuit 9. OFF Isolation and Bandwidth



Test Circuit 10. Channel-to-Channel Crosstalk

OUTLINE DIMENSIONS



COMPLIANT TO JEDEC STANDARDS MO-153-AE

28-Lead Thin Shrink Small Outline Package [TSSOP]
(RU-28)
Dimensions shown in millimeters

Revision History

Location	Page
3/16—Data Sheet changed from REV. A to REV. B.	
Changes to ORDERING GUIDE	5
Updated OUTLINE DIMENSIONS	11
5/02—Data Sheet changed from REV. 0 to REV. A.	
Edits to FEATURES and PRODUCT HIGHLIGHTS	1
Changes to SPECIFICATIONS	2
Edits to ABSOLUTE MAXIMUM RATINGS notes	5
Edits to TPCs 2, 3, 4, 6–9, 12, 14	7–8
Edits to Test Circuits 9 and 10	10

D01001-0-3/16(B)